



Material Content Data Sheet



Sales Product Name		ILD6150		Issued		19. July 2018		
MA#		MA001040794						
Package		PG-DSO-8-27		Weight*		84.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.275	2.70	2.70	27031	27031
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.728	0.86		8645	
wire	non noble metal	copper	7440-50-8	29.548	35.10	36.01	351008	360193
	noble metal	gold	7440-57-5	0.241	0.29	0.29	2861	2861
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1168
encapsulation	plastics	epoxy resin	-	4.523	5.37		53729	
	inorganic material	silicondioxide	60676-86-0	44.540	52.91	58.40	529113	584010
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8258	8258
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8607	8607
glue	plastics	epoxy resin	-	0.190	0.23		2260	
	noble metal	silver	7440-22-4	0.571	0.68	0.91	6780	9040
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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